

This listing of claims will replace all prior versions, and listings of claims in the application:

Listing of Claims:

20. (presently amended) A pad assembly for plating and polishing a semiconductor workpiece, comprising:

a cylindrical anode having an outer surface; and

a plurality of pad strips mounted on the cylindrical anode ~~such that the plurality of pad strips~~
which protrudes from the outer surface of the cylindrical anode and configured to planarize and fill
cavities on the semiconductor workpiece.

21. (original) The pad assembly according to claim 20, wherein the cylindrical anode is adapted to rotate about a first axis.

22. (presently amended) The pad assembly according to claim 20, wherein ~~plating is performed~~
~~when the pad strips are not in contact with the workpiece, and polishing is performed when the pad~~
~~strips are in contact with~~ polish the workpiece.

23. (original) The pad assembly according to claim 20, wherein the workpiece comprises one of a wafer, a flat panel, and a magnetic film head.

24. (presently amended) A pad assembly for plating and polishing a semiconductor workpiece, comprising:

a circular or donut shaped anode having a planar top surface; and

a plurality of pad strips mounted on the planar top surface of the anode such that the plurality of pad strips protrude from the top surface of the anode.

25. (original) The pad assembly according to claim 24, wherein the anode is adapted to rotate about a first axis.

26. (presently amended) The pad assembly according to claim 24, ~~wherein plating is performed when the pad strips are not in contact with the workpiece, and polishing is performed when the pad strips are in contact with~~ polish the workpiece.

27. (original) The pad assembly according to claim 24, wherein the workpiece comprises one of a wafer, a flat panel, and a magnetic film head.

30. (presently amended) An anode assembly for plating a semiconductor workpiece, comprising:
an anode having an outer surface; and
a plurality of pad strips or fixed features attached on the anode such that the plurality of pad strips protrude from the outer surface of the anode and is configured to planarize and fill cavities on the semiconductor workpiece.

31. (original) The pad assembly according to claim 30, wherein the anode is adapted to rotate about a first axis.

32. (presently amended) The pad assembly according to claim 30, wherein ~~plating is performed when the pad strips or fixed features are in proximity to the workpiece.~~

33. (presently amended) The pad assembly according to claim 32, wherein the proximity between the pad strips or fixed features and are within 0-5 mm from the workpiece provides a meniscus solution of electrolyte for plating the semiconductor workpiece.